ABSTRACT OF THE DISCLOSURE

POLISHING APPARATUS

The polishing apparatus comprises a turn table, which polishes a semiconductor wafer, and a holding and pressing part, which holds and presses the semiconductor wafer against a polishing surface of the turn table. The holding and pressing part transmits a force from an air bag to the semiconductor wafer via a pressurized fluid layer to thereby press the semiconductor wafer against the polishing surface via the pressurized fluid layer, so that the semiconductor wafer can be polished. Thereby, it is possible to uniformly polish the semiconductor wafer.

(Fig. 1)

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